

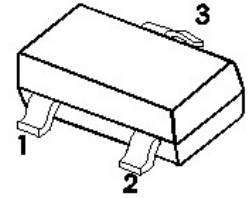
SOT-23 Plastic-Encapsulate Schottky Barrier Diode

Features

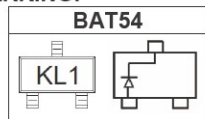
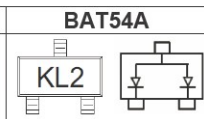
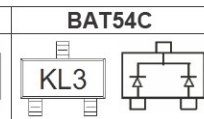
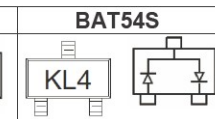
- High Current Capability
- Low Forward Voltage Drop
- Extremely Fast Switching Speed

Mechanical Data

- SOT-23 Small Outline Plastic Package
- Epoxy UL: 94V-0
- Mounting Position: Any

SOT-23


MARKING:

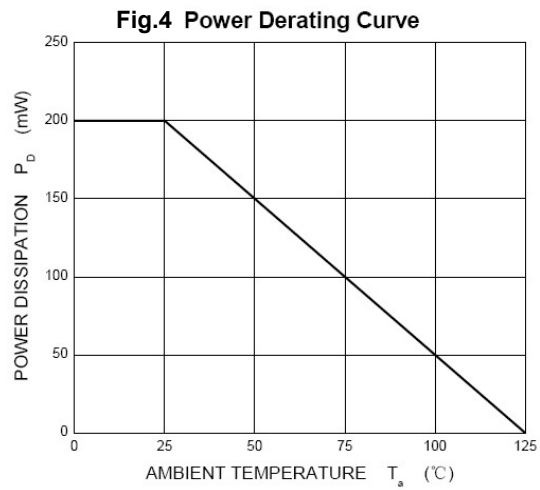
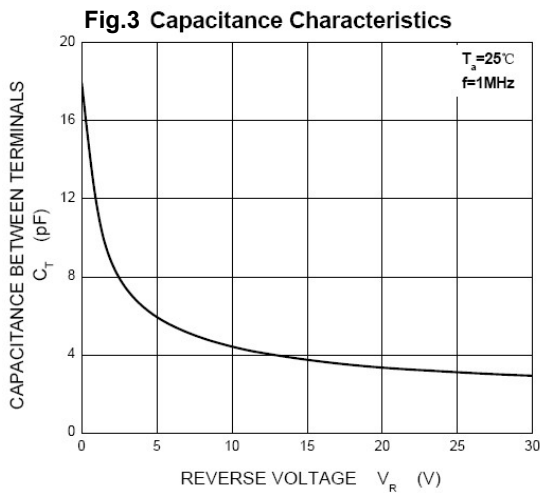
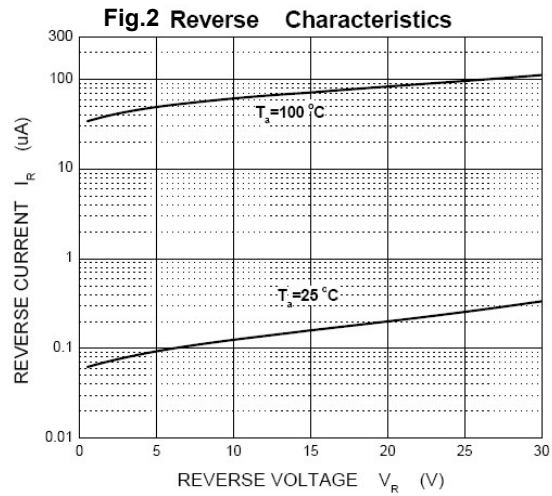
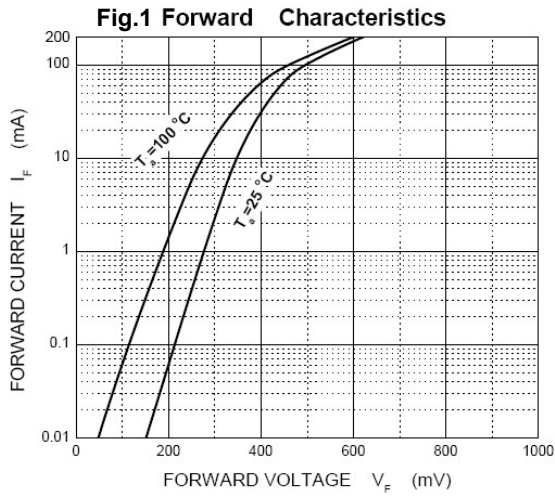
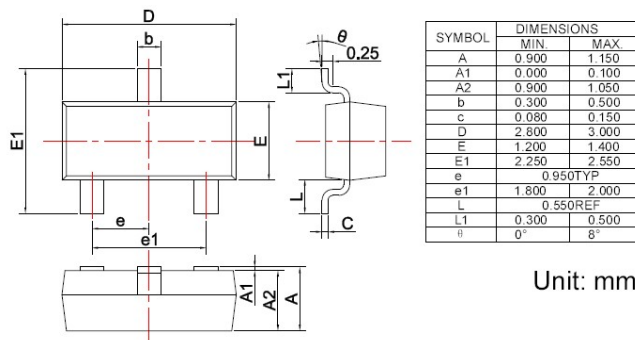
BAT54	BAT54A	BAT54C	BAT54S
			

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

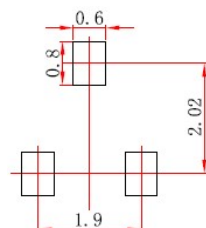
Parameters	Symbol	Limit	Unit
Maximum repetitive peak reverse voltage	VRRM	30	V
Maximum RMS voltage	VRMS	21	V
Maximum DC blocking voltage	VDC	30	V
Maximum average forward rectified current	IFM	200	mA
Peak forward surge current 8.3 ms single half sine-wave	IFSM	600	mA
Typical thermal resistance	R θ JA	500	°C/W
Power Dissipation	PD	200	mW
Junction Temperature	T _j	125	°C
Storage temperature range	TSTG	-50-+150	°C

Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified).

Parameters	Symbol	Test conditions	Min	Typ	Max	Unit
Maximum forward voltage	VF1	IF = 0.1mA			240	mV
	VF2	IF = 1.0mA			320	
	VF3	IF = 10mA			400	
	VF4	IF = 30mA			500	
	VF5	IF = 100mA			1000	
Maximum reverse breakdown voltage	VR	IR=100uA	30			V
Maximum reverse current	IR	VR=25V			2.0	uA
Type junction capacitance	C _j	VR = 1.0V, f = 1MHz			10	pF
Reverse Recovery time	trr	IF=IR=10mA Irr=0.1XIR, RL=100 Ω			5	ns

Typical Characteristics

SOT-23 PACKAGE OUTLINE Plastic surface mounted package


Precautions: PCB Design(Recommended land dimensions for SOT-23 diode. Electrode patterns for PCBs)



Note:
 1. Controlling dimension; In millimeters.
 2. General tolerance: ±0.05mm.
 3. The pad layout is for reference purposes only.

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